

DFCT65G51LDHAA-RD2

Part Number/Tape & Reel information

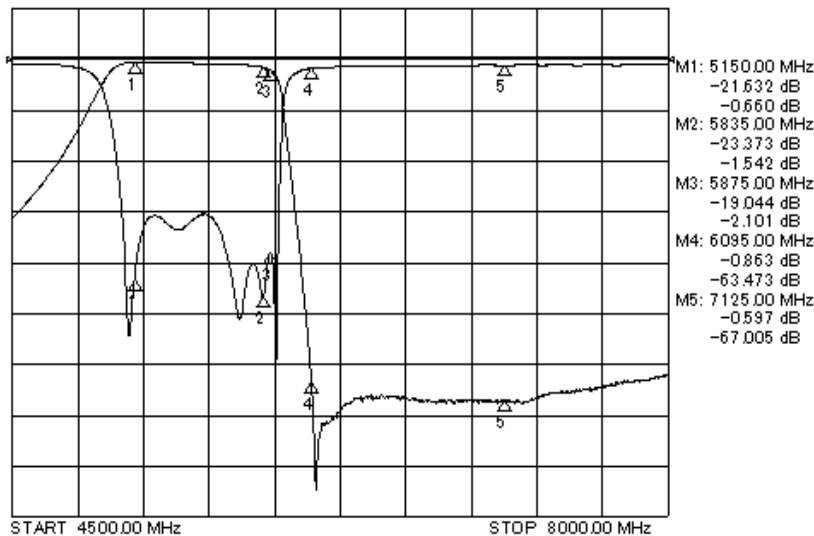
Part Number	Packaging	MOQ
DFCT65G51LDHAA-RD2	330 mm dia. reel	2000 pcs/reel

Specifications -40 to +85°C

Parameter	IN to OUT
Center Frequency	F0 : 5512.5 MHz
Band Width (BW)	F0 +/- 362.5 MHz
Insertion Loss at BW	2.5 dB max. (at 25°C) 2.9 dB max.
Insertion Loss at 5150 ~ 5835 MHz	2.0 dB max. (at 25°C) 2.2 dB max.
Ripple at BW	2.5 dB max.
V.S.W.R. at BW	2.0 max.
Input Power	1.0 W max.
Attenuation Absolute value	6095 ~ 7125 MHz 60dB min.
Characteristic Impedance	50 Ohms

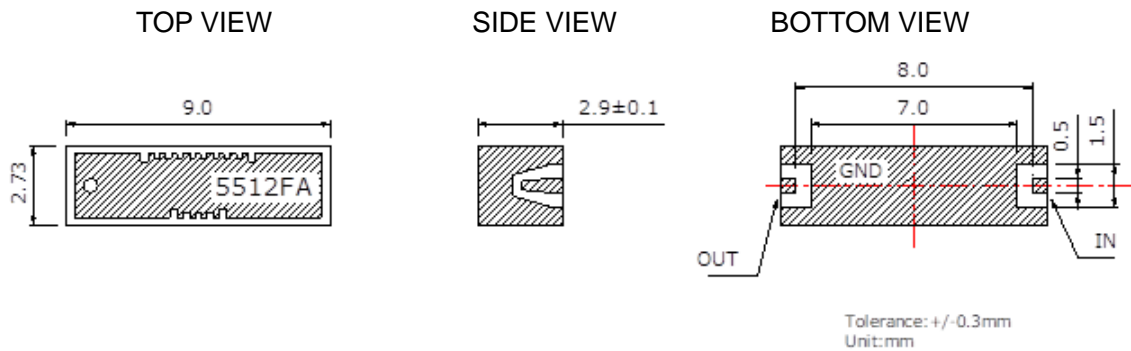
Frequency Response

S11 log MAG 5 dB/ REF 0 dB
S21 log MAG 10 dB/ REF 0 dB

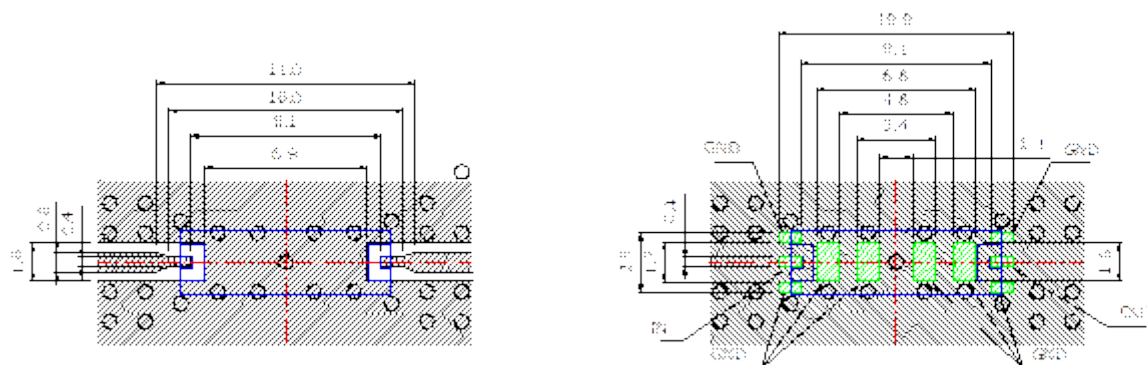


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Dimensions and Marking



Recommend Land Pattern (reference)

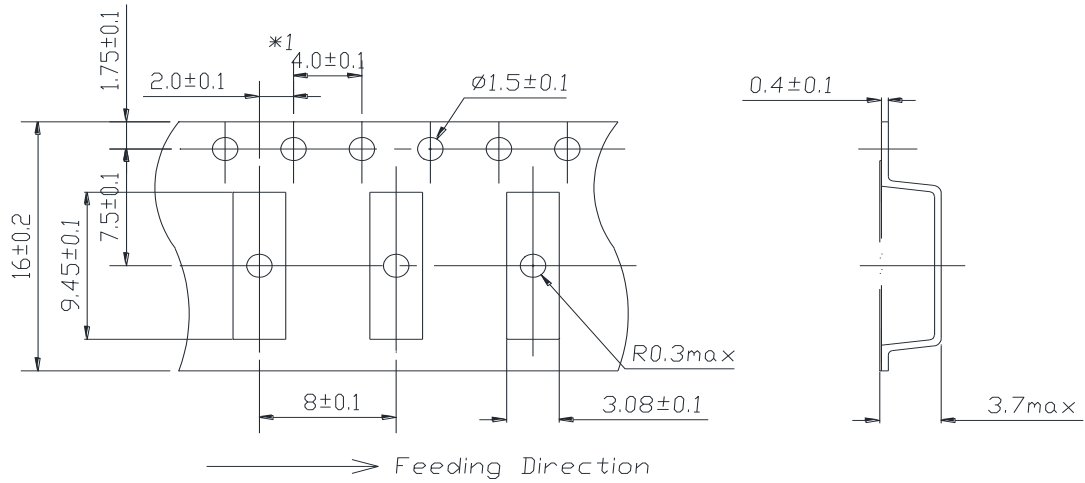


Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the BT resin board (t = 0.4, dielectric constant = 3.6, copper plating on both surfaces).

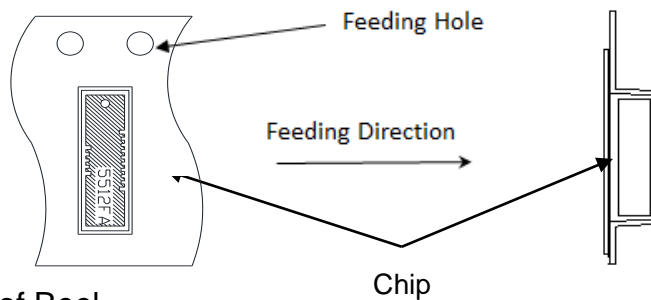
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Dimensions of Carrier Tape

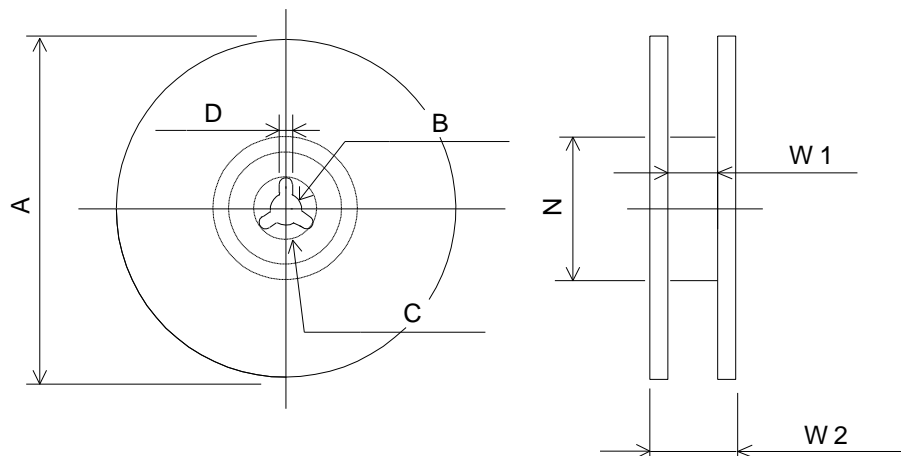
*1 Cumulative tolerance of max. ± 0.3 every 10 pitches



DIMENSIONS : mm



Dimensions of Reel



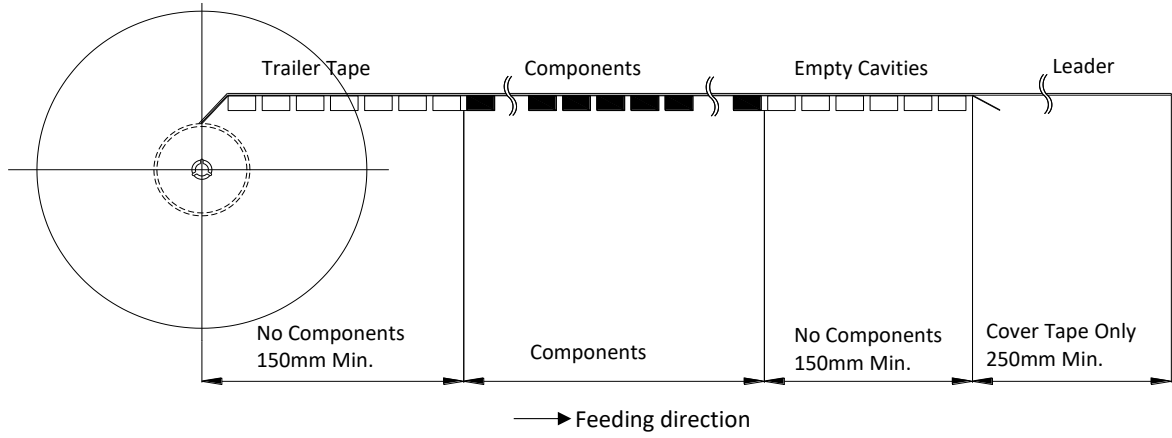
Murata Part Number	A+/-2.0	B+/-0.5	C+/-0.8	D+/-0.5	N (min.)	W1+/-1.5	W2 (max.)
DFCT65G51LDHAA-RD2	330	dia 13	dia 21	2.4	50	16.5	27

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*Note: All the technical data and information contained herein are subject to change without advanced notice.

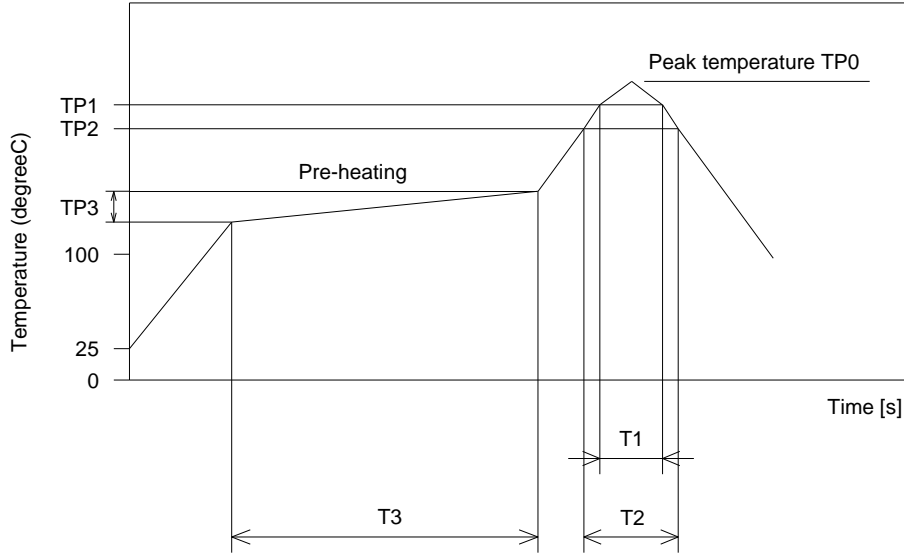
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Taping Condition



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Reflow Soldering Standard Conditions



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)	T3 (s)
Reflow standard condition	Sn-3Ag-0.5Cu solder	255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120
Test condition of reflow heat resistance		255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120

Reflow soldering is available 2 times for above test condition of reflow heat resistance.